

# **SUBSTRATE AND METHOD OF FORMING SUBSTRATE FOR FLUID EJECTION DEVICE**

## Abstract of the Disclosure

A method of forming an opening through a substrate includes etching into the substrate from a first side so as to form a first portion of the opening, etching into the substrate from a second side opposite the first side so as to form a second portion of the opening, continuing etching into the substrate from at least one of the first side and the second side toward the other of the first side and the second side so as to communicate the first portion and the second portion of the opening, and etching into the substrate from an interface between the first portion and the second portion of the opening, including etching toward the second side of the substrate and forming a third portion of the opening.

卷之三